

TRANSPORTATION RAMM CHIPSEAL DATA

(to be completed for each seal layer on each road section)

| | |
|-----------------------|--------------------------|
| SUBDIVISION | |
| ROAD NO / NAME | |
| CONTRACTOR | |
| START Mtr. | START DESCRIPTION |
| END Mtr. | END DESCRIPTION |
| WIDTH | DATE OF WORK |

| | |
|--|--|
| Seal Type | |
| Seal Reason | |
| Area Sealed (m^2) | |
| Chip Grading (e.g. 3/5) | |
| Binder Type (e.g. B180/200) | |
| Chip Source Company | |
| Chip Source Quarry | |
| Total Volume of Binder Used (Litres) | |
| Temperature of Binder ($^{\circ}C$) | |
| Residual Binder Rate (L/m^2) | |
| Cutter (e.g. 3 pph Kero) | |
| Other Additives with concentrations (e.g. Polymer modification RS1, 3%) | |

Surfacing Chip PSV testing form attached

Sealing Notes

(e.g. Weather, Temp)